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PATENT  
Att'y. Dkt. No. AMATH4471/CP/COPPER/JS

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:  
Zheng et al.

Serial No.: 09/614 407

Confirmation No.: 1803

Filed: July 12, 2000

**For:** Method of Application of  
Electrical Biasing to  
Enhance Metal Deposition

**Assistant Commissioner for Patents  
Washington, D.C. 20231**

**Dear Sir,**

Group Art Unit: 1741

**Examiner:** Smith-Hicks, E

**Smith-Hicks, E.**

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**JUL 15 2002**

**GROUP 1106**

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**37 CFR 1.8**

I hereby certify that this correspondence is being transmitted to the Patent and Trademark Office to the fax number indicated by the Examiner, namely (703) 672-4010 in the attention of the named Examiner, on the date below:

5/30/02 Am. Gramm  
Date Art O. Pham

**RESPONSE TO OFFICE ACTION DATED APRIL 10, 2002**

In response to the Office Action dated April 10, 2002, having a shortened statutory period for response set to expire on July 10, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. The Commissioner is authorized to charge Deposit Account No. 20-0782/4471/CPI/COPPER/PJS in the amount of \$396.00 for the addition of 22 new dependent claims and any other fees necessary to make this response timely.

**IN THE SPECIFICATION:**

Please amend the specification at page 15, line 31, as follows:

**Step 2:** This step involves attracting the metal ions in close proximity to the entire topography of the seed layer on the substrate including the portion of the seed